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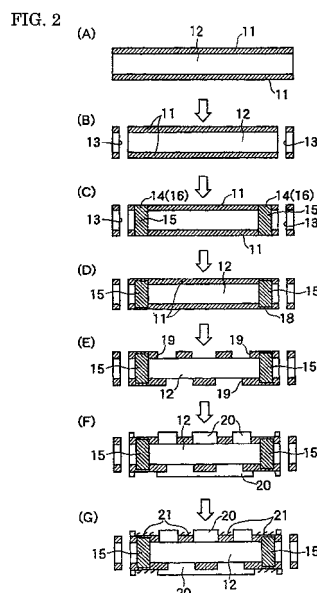
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(54) **PRINTED CIRCUIT BOARD AND PRODUCTION METHOD THEREFOR, AND LAMINATED PRINTED CIRCUIT BOARD**

(57) A print circuit board including a dielectric substrate (12) having via-holes (16) perforated there-through, an implant material (15) filled in the via-holes (16) and selected from a group consisting of oxygen free copper, phosphorus-deoxidized copper and tough pitch copper, and interconnect patterns formed on both surfaces of the substrate (12) and electrically connected to the implant material (15). The probability of generating the deficiencies in the print circuit board of the present invention is reduced under the conditions of the repeated heating and cooling between higher temperatures and lower temperatures to which the print circuit board is likely exposed because the via-holes (16) are made of the highly resistant oxygen free copper, phosphorus-deoxidized copper or tough pitch copper, and the print circuit board is used for a longer period of time as a highly heat-resistant print circuit board.



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